



**EXPEDITED PROCEDURE – EXAMINING GROUP 2827**

**09/893588**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Takashi Kumamoto

Examiner: Alonzo Chambliss

Serial No.: 09/893588

Group Art Unit: 2827

Filed: June 29, 2001

Docket No.: 884.A98US1

Title: MULTI-PURPOSE PLANARAZING/BACK-GRIND/PRE-UNDERFULL  
ARRANGEMENTS FOR BUMPED WAFERS AND DIE

Assignee: Intel Corporation

Customer No.: 21186

**AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the final Office Action mailed August 1, 2003, please amend the application as follows: